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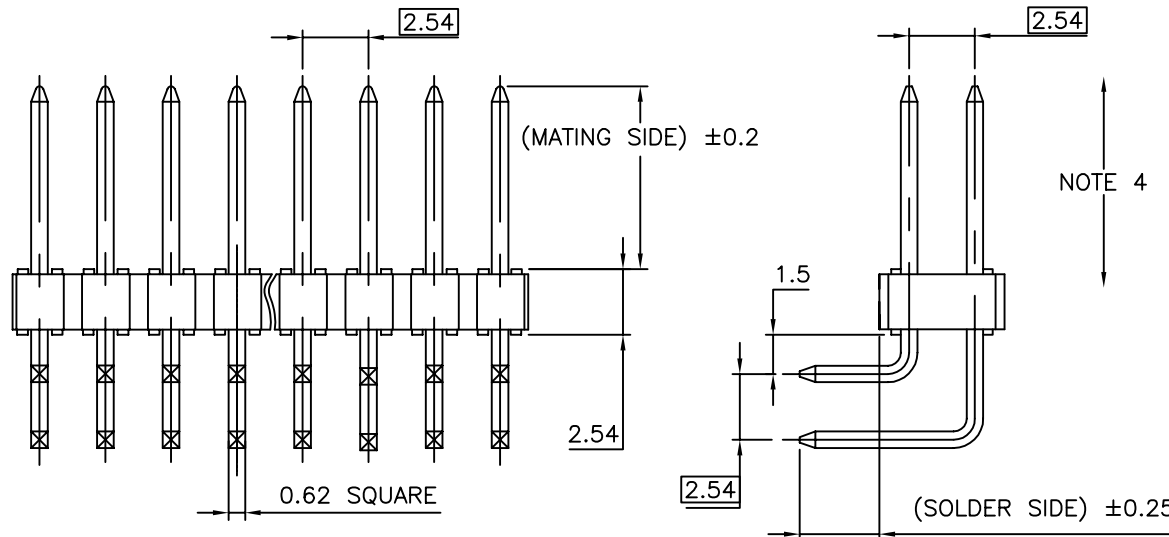
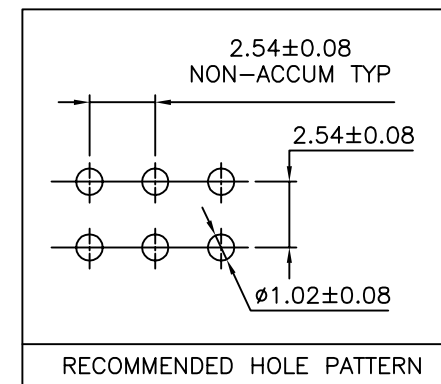
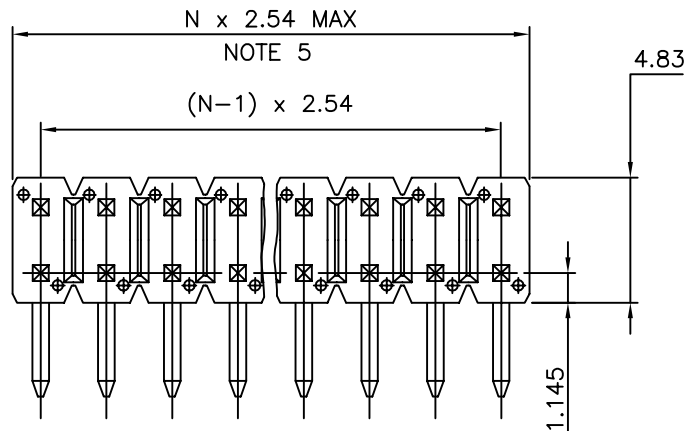
PRODUCT NUMBER




77317-YXX-XXLF

- WHEN REQUIRED, ADD SUFFIX LETTER "LF" INDICATES THE PRODUCT IS RoHS COMPATIBLE, SEE NOTE 7
- TOTAL NB OF POSITIONS 04 TO 72
- PIN STYLE SEE SHEET 2
- PLATING SEE SHEET 2

NOTES:

- HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
- PIN MATERIAL : PHOSPHOR BRONZE
- PRODUCT PACKAGED IN POLY BAGS.
- 9N MIN RETENTION IN EITHER DIRECTION
- TO DETERMINE DIMENSIONS :  
N = NUMBER OF POSITIONS PER ROW  
EXAMPLE : 8 POS  $N \times 2.54 = 20.32\text{mm}$
- UNDERPLATING :  $1.27\mu\text{m}$  Ni MIN
- RoHS COMPATIBLE PRODUCT SPECIFICATIONS
  - PLATING:
    - "LF" MEANS THE PRODUCT IS LEAD-FREE,  $2\mu\text{m}$  MINIMUM MATTE TIN OVER  $1.27\mu\text{m}$  MINIMUM NICKEL UNDERPLATE.
  - MANUFACTURING PROCESS COMPATIBILITY
    - THE HOUSING WILL WITHSTAND EXPOSURE TO  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
  - LABELING:
    - MEETS PACKAGING SPECS AS PER GS-14-920
  - LEGAL STATEMENT: SEE GS-22-008



mat'l. code SEE NOTES				tolerances unless otherwise specified		CUSTOMER COPY	 <b>ELECTRONICS</b> www.fciconnect.com	title	
ltr	ecn	no	dr	date				UNSHR.HEADER	
AA	F04-0167	JCO		04.04.05	linear	.X ±0.3	projection 	RA DR TMT	
AB	F04-0362	LMU		04.11.29		.XX ±0.15		product family	
					angles	.XXX ±0.05		BERGSTIK	
V	F10306	LMU	01.05.21	dr	D.LE	01.01.24	mm 	size	
W	F20353	LMU	02.06.18	eng	JM.C	01.01.24		dwg no	
X	F20592	JCO	02.11.26	chr	JM.C	01.01.24		77317	
Y	F04-0129	LMU	04.02.04	appd	JF.N	01.01.24	scale 5:1	A3	
sheet	revision	AB	X					code	
index	sheet	1	2					213	
								sheet	
								1 of 2	

## CATALOGUE RANGE

PLATING	PIN STYLE	MATING	SOLDER
1/4/8	03	5.84	2.54
1/4/8	04	5.84	3.05
1/4/8	12	6.8	3.05

## PLATING

- 1 = 0.76µm GOLD ON CONTACT AREA  
3.81µm TIN-LEAD ON TAIL
- 4 = 3.81µm TIN-LEAD ON CONTACT AREA  
AND ON TAIL
- 8 = 0.38µm GOLD ON CONTACT AREA  
3.81µm TIN-LEAD ON TAIL
- WHEN "LF" IS REQUIRED, 2µm MATTE  
TIN OVER 1.27µm MIN NICKEL IS  
PROVIDED INSTEAD OF TIN-LEAD

## APPLICATION SPECIFIC

PLATING	PIN STYLE	MATING	SOLDER
1/4/8	01	5.72	2.57
1/4/8	14	10	2.7
1/4/8	15	7	16.4
1/4/8	16	7.8	13.5
1/4/8	17	7.48	1.6

## PLATING

- 1 = 0.76µm GOLD ON CONTACT AREA  
3.81µm TIN-LEAD ON TAIL
- 4 = 3.81µm TIN-LEAD ON CONTACT AREA  
AND ON TAIL
- 8 = 0.38µm GOLD ON CONTACT AREA  
3.81µm TIN-LEAD ON TAIL
- WHEN "LF" IS REQUIRED, 2µm MATTE  
TIN OVER 1.27µm MIN NICKEL IS  
PROVIDED INSTEAD OF TIN-LEAD



B

A

B

C

D

mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		 <b>ELECTRONICS</b> <a href="http://www.fciconnect.com">www.fciconnect.com</a>	
ltr	ecn no	dr	date	linear				projection		title	
S	F00141	LMU	00.02.28							UNSHR.HEADER	
T	F10119	DLE	01.01.24							RA DR TMT	
U	F10183	LMU	01.03.30	angles						product family	
V	F20353	LMU	02.06.18	dr	D.LE	01.01.24			BERGSTIK		code
W	F20592	JCO	02.11.26	engr	JM.C	01.01.24			size		213
X	F04-0362	LMU	04.11.29	chr	JM.C	01.01.24			dwg no		sheet
				appd	JF.N	01.01.24			A3		2 of -
sheet index		revision sheet									